

74LVC2G04

Dual inverter

Rev. 04 — 25 July 2007

Product data sheet

1. General description

The 74LVC2G04 provides the dual inverting buffer.

Inputs can be driven from either 3.3 V or 5 V devices. These features allow the use of these devices in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using I_{OFF}. The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2. Features

- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant inputs for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- ±24 mA output drive (V_{CC} = 3.0 V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options
- Specified from –40 °C to +85 °C and –40 °C to +125 °C.

3. Ordering information

Table 1. Ordering information

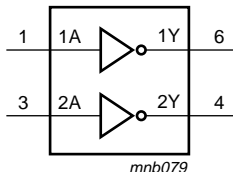
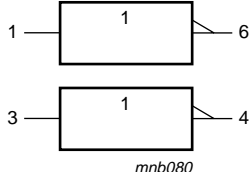
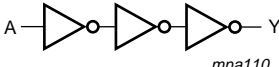
| Type number | Package | | | Version |
|-------------|-------------------|-------|---|---------|
| | Temperature range | Name | Description | |
| 74LVC2G04GW | -40 °C to +125 °C | SC-88 | plastic surface-mounted package; 6 leads | SOT363 |
| 74LVC2G04GV | -40 °C to +125 °C | TSOP6 | plastic surface-mounted package (TSOP6); 6 leads | SOT457 |
| 74LVC2G04GM | -40 °C to +125 °C | XSON6 | plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm | SOT886 |
| 74LVC2G04GF | -40 °C to +125 °C | XSON6 | plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm | SOT891 |

4. Marking

Table 2. Marking

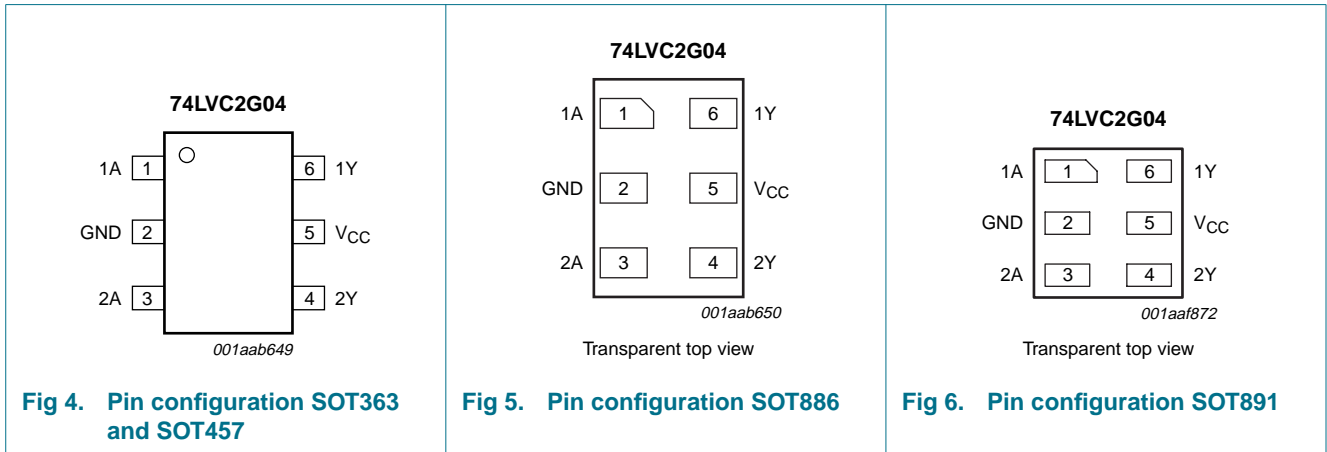
| Type number | Marking code |
|-------------|--------------|
| 74LVC2G04GW | V4 |
| 74LVC2G04GV | V04 |
| 74LVC2G04GM | V4 |
| 74LVC2G04GF | V4 |

5. Functional diagram

| | | |
|---|---|---|
|  <p>Fig 1. Logic symbol</p> |  <p>Fig 2. IEC logic symbol</p> |  <p>Fig 3. Logic diagram (one gate)</p> |
|---|---|---|

6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|-----------------|-----|----------------|
| 1A | 1 | data input |
| GND | 2 | ground (0 V) |
| 2A | 3 | data input |
| 2Y | 4 | data output |
| V _{CC} | 5 | supply voltage |
| 1Y | 6 | data input |

7. Functional description

Table 4. Function table^[1]

| Input | Output |
|-------|--------|
| nA | nY |
| L | H |
| H | L |

[1] H = HIGH voltage level;
L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|-------------------------------|-------------|----------------|------|
| V_{CC} | supply voltage | | -0.5 | +6.5 | V |
| I_{IK} | input clamping current | $V_I < 0$ V | -50 | - | mA |
| V_I | input voltage | | [1] -0.5 | +6.5 | V |
| I_{OK} | output clamping current | $V_O > V_{CC}$ or $V_O < 0$ V | - | ± 50 | mA |
| V_O | output voltage | Active mode | [1][2] -0.5 | $V_{CC} + 0.5$ | V |
| | | Power-down mode | [1][2] -0.5 | +6.5 | V |
| I_O | output current | $V_O = 0$ V to V_{CC} | - | ± 50 | mA |
| I_{CC} | supply current | | - | 100 | mA |
| I_{GND} | ground current | | -100 | - | mA |
| P_{tot} | total power dissipation | $T_{amb} = -40$ °C to +125 °C | [3] - | 250 | mW |
| T_{stg} | storage temperature | | -65 | +150 | °C |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When $V_{CC} = 0$ V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For SC-88 and SC-74 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.
For XSON6 packages: above 45 °C the value of P_{tot} derates linearly with 2.4 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---------------------|-------------------------------------|---------------------------------|------|-----|----------|------|
| V_{CC} | supply voltage | | 1.65 | - | 5.5 | V |
| V_I | input voltage | | 0 | - | 5.5 | V |
| V_O | output voltage | Active mode | 0 | - | V_{CC} | V |
| | | Power-down mode; $V_{CC} = 0$ V | 0 | - | 5.5 | V |
| T_{amb} | ambient temperature | | -40 | - | +125 | °C |
| $\Delta t/\Delta V$ | input transition rise and fall rate | $V_{CC} = 1.65$ V to 2.7 V | - | - | 20 | ns/V |
| | | $V_{CC} = 2.7$ V to 5.5 V | - | - | 10 | ns/V |

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|------------------|---------------------------|---|-----------------------|--------------------|---------------------|-----------------------|---------------------|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 1.65 V to 1.95 V | 0.65V _{CC} | - | - | 0.65V _{CC} | - | V |
| | | V _{CC} = 2.3 V to 2.7 V | 1.7 | - | - | 1.7 | - | V |
| | | V _{CC} = 2.7 V to 3.6 V | 2.0 | - | - | 2.0 | - | V |
| | | V _{CC} = 4.5 V to 5.5 V | 0.7V _{CC} | - | - | 0.7V _{CC} | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 1.65 V to 1.95 V | - | - | 0.35V _{CC} | - | 0.35V _{CC} | V |
| | | V _{CC} = 2.3 V to 2.7 V | - | - | 0.7 | - | 0.7 | V |
| | | V _{CC} = 2.7 V to 3.6 V | - | - | 0.8 | - | 0.8 | V |
| | | V _{CC} = 4.5 V to 5.5 V | - | - | 0.3V _{CC} | - | 0.3V _{CC} | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | |
| | | I _O = -100 μA; V _{CC} = 1.65 V to 5.5 V | V _{CC} - 0.1 | - | - | V _{CC} - 0.1 | - | V |
| | | I _O = -4 mA; V _{CC} = 1.65 V | 1.2 | - | - | 0.95 | - | V |
| | | I _O = -8 mA; V _{CC} = 2.3 V | 1.9 | - | - | 1.7 | - | V |
| | | I _O = -12 mA; V _{CC} = 2.7 V | 2.2 | - | - | 1.9 | - | V |
| | | I _O = -24 mA; V _{CC} = 3.0 V | 2.3 | - | - | 2.0 | - | V |
| | | I _O = -32 mA; V _{CC} = 4.5 V | 3.8 | - | - | 3.4 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | |
| | | I _O = 100 μA; V _{CC} = 1.65 V to 5.5 V | - | - | 0.10 | - | 0.10 | V |
| | | I _O = 4 mA; V _{CC} = 1.65 V | - | - | 0.45 | - | 0.70 | V |
| | | I _O = 8 mA; V _{CC} = 2.3 V | - | - | 0.30 | - | 0.45 | V |
| | | I _O = 12 mA; V _{CC} = 2.7 V | - | - | 0.40 | - | 0.60 | V |
| | | I _O = 24 mA; V _{CC} = 3.0 V | - | - | 0.55 | - | 0.80 | V |
| | | I _O = 32 mA; V _{CC} = 4.5 V | - | - | 0.55 | - | 0.80 | V |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | ±0.1 | ±5 | - | ±20 | μA |
| I _{OFF} | power-off leakage current | V _{CC} = 0 V; V _I or V _O = 5.5 V | - | ±0.1 | ±10 | - | ±20 | μA |
| I _{CC} | supply current | V _I = 5.5 V or GND; I _O = 0 A; V _{CC} = 1.65 V to 5.5 V | - | 0.1 | 10 | - | 40 | μA |
| ΔI _{CC} | additional supply current | per pin; V _{CC} = 2.3 V to 5.5 V; V _I = V _{CC} - 0.6 V; I _O = 0 A | - | 5 | 500 | - | 5000 | μA |
| C _I | input capacitance | V _{CC} = 3.3 V; V _I = GND to V _{CC} | - | 2.5 | - | - | - | pF |

[1] All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|-----------------|-------------------------------|--|------------------|--------------------|-----|-------------------|-----|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| t _{pd} | propagation delay | nA to nY; see Figure 7 ^[2] | | | | | | |
| | | V _{CC} = 1.65 V to 1.95 V | 1.0 | 3.5 | 8.0 | 1.0 | 9.5 | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 1.0 | 2.2 | 4.4 | 1.0 | 5.4 | ns |
| | | V _{CC} = 2.7 V | 1.0 | 2.7 | 5.2 | 1.0 | 7.0 | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 0.5 | 2.7 | 4.1 | 0.5 | 5.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V | 1.0 | 1.9 | 3.2 | 1.0 | 3.8 | ns |
| C _{PD} | power dissipation capacitance | V _I = GND to V _{CC} ; V _{CC} = 3.3 V ^[3] | - | 13.5 | - | - | - | pF |

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

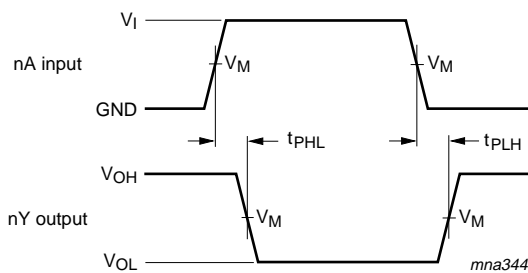
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

∑(C_L × V_{CC}² × f_o) = sum of outputs.

12. AC waveforms



Measurement points are given in [Table 9](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. The input nA to output nY propagation delays

Table 9. Measurement points

| Supply voltage | Input | Output |
|------------------|-------------|-------------|
| V_{CC} | V_M | V_M |
| 1.65 V to 1.95 V | $0.5V_{CC}$ | $0.5V_{CC}$ |
| 2.3 V to 2.7 V | $0.5V_{CC}$ | $0.5V_{CC}$ |
| 2.7 V | 1.5 V | 1.5 V |
| 3.0 V to 3.6 V | 1.5 V | 1.5 V |
| 4.5 V to 5.5 V | $0.5V_{CC}$ | $0.5V_{CC}$ |



Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 8. Load circuit for switching times

Table 10. Test data

| Supply voltage | Input | Load | | | V_{EXT} |
|------------------|----------|---------------|-------|--------------|--------------------|
| V_{CC} | V_I | $t_r = t_f$ | C_L | R_L | t_{PLH}, t_{PHL} |
| 1.65 V to 1.95 V | V_{CC} | ≤ 2.0 ns | 30 pF | 1 k Ω | open |
| 2.3 V to 2.7 V | V_{CC} | ≤ 2.0 ns | 30 pF | 500 Ω | open |
| 2.7 V | 2.7 V | ≤ 2.5 ns | 50 pF | 500 Ω | open |
| 3.0 V to 3.6 V | 2.7 V | ≤ 2.5 ns | 50 pF | 500 Ω | open |
| 4.5 V to 5.5 V | V_{CC} | ≤ 2.5 ns | 50 pF | 500 Ω | open |

13. Package outline

Plastic surface-mounted package; 6 leads

SOT363

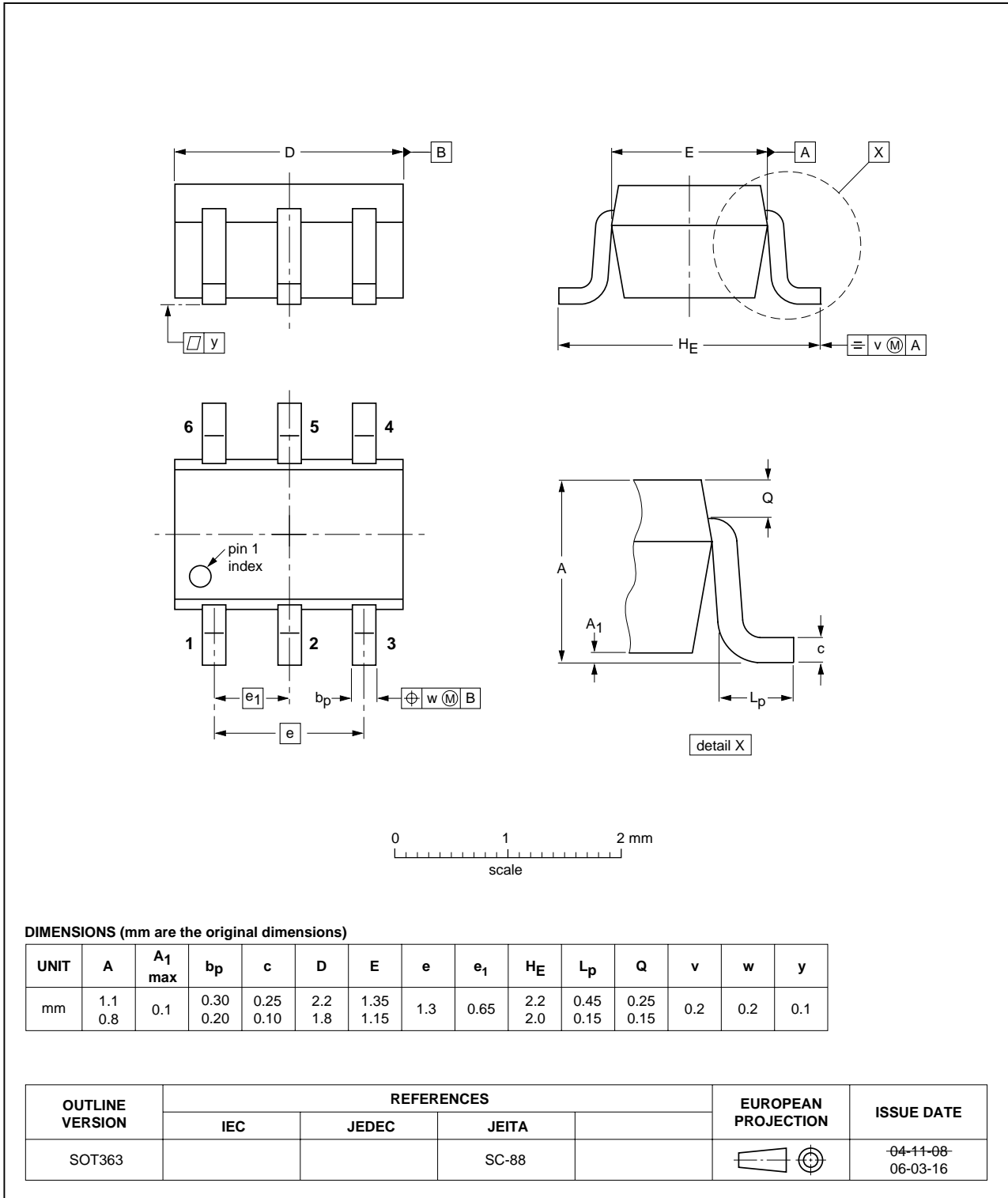


Fig 9. Package outline SOT363 (SC-88)

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

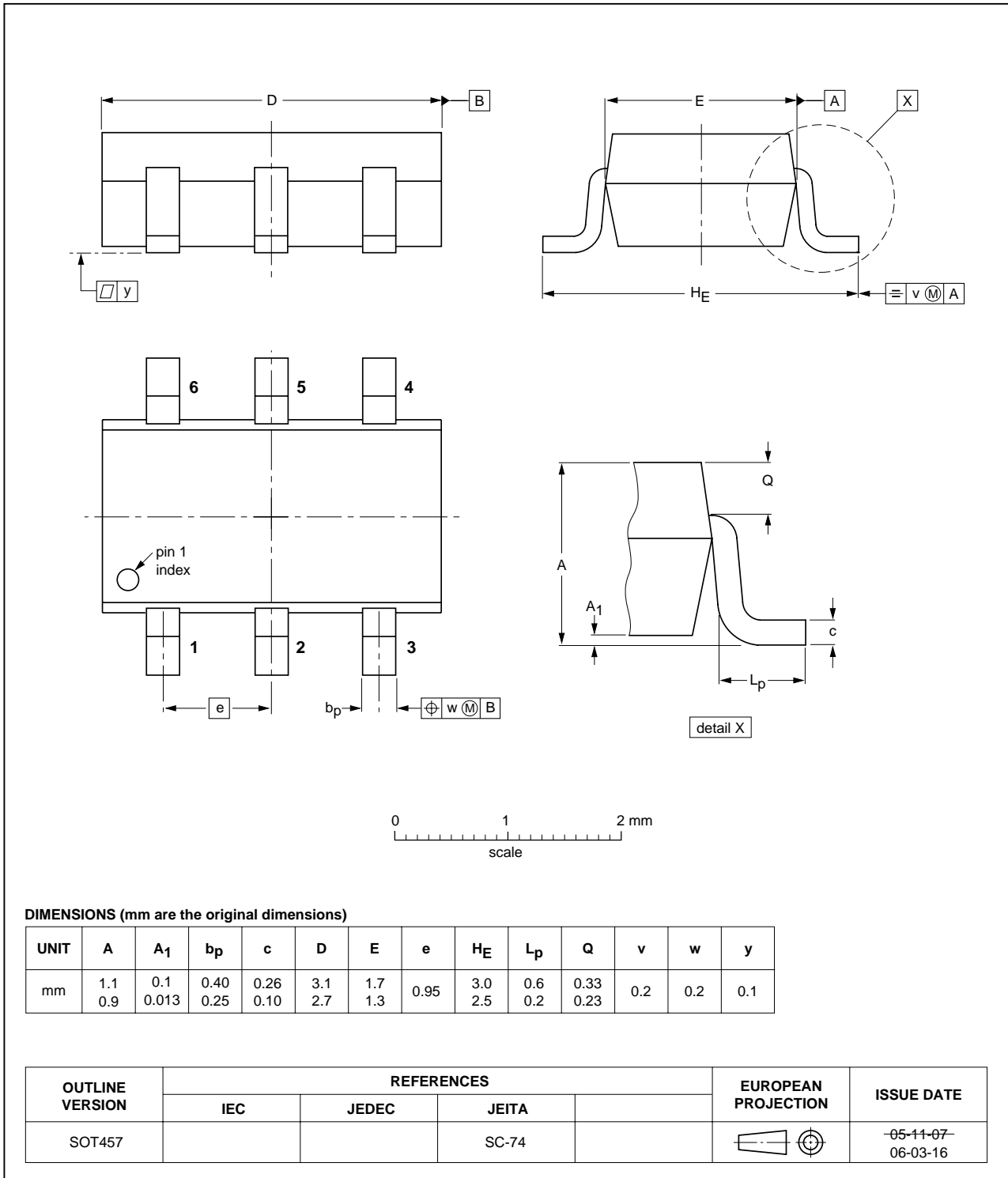


Fig 10. Package outline SOT457 (SC-74)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886



Fig 11. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891



Fig 12. Package outline SOT891 (XSON6)

14. Abbreviations

Table 11. Abbreviations

| Acronym | Description |
|---------|---|
| CMOS | Complementary Metal Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

15. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|---|-----------------------|---------------|-------------|
| 74LVC2G04_4 | 20070725 | Product data sheet | - | 74LVC2G04_3 |
| Modifications: | • New package outline drawing for XSON6/SOT891. | | | |
| 74LVC2G04_3 | 20070216 | Product data sheet | - | 74LVC2G04_2 |
| 74LVC2G04_2 | 20040915 | Product specification | - | 74LVC2G04_1 |
| 74LVC2G04_1 | 20030722 | Product specification | - | - |

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16.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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18. Contents

1 **General description** 1

2 **Features** 1

3 **Ordering information** 2

4 **Marking** 2

5 **Functional diagram** 2

6 **Pinning information** 3

6.1 Pinning 3

6.2 Pin description 3

7 **Functional description** 3

8 **Limiting values** 4

9 **Recommended operating conditions** 4

10 **Static characteristics** 5

11 **Dynamic characteristics** 6

12 **AC waveforms** 6

13 **Package outline** 8

14 **Abbreviations** 12

15 **Revision history** 12

16 **Legal information** 13

16.1 Data sheet status 13

16.2 Definitions 13

16.3 Disclaimers 13

16.4 Trademarks 13

17 **Contact information** 13

18 **Contents** 14

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